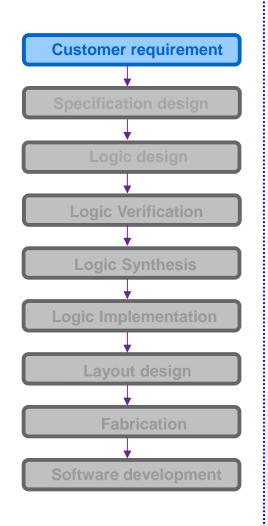


To product one chip, basically, we need to process through 9 *steps*:

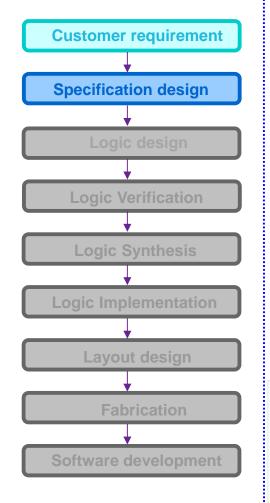
- Step 1 is processed by the Marketing or Selling department.
- Step 2, 3, 4, and 5 are processed by the Design department and are called Frontend Design.
- Step 6 and 7 are processed by the Design department and are called Backtend Design.
- Step 8 is processed by the Manufacture department.
- Step 9 is processed by the Software department.



Step 1: Customer Requirement

Marketers or sellers, along with engineers, will contact with customers to negotiate about demands or predicts market's needs.

- ◆ The requirements will be written in a contract by common language.
- Customers come from America, Europe and Asia's companies
- Our main products: MPU, MCU, SoCs for mobile phones, car information systems

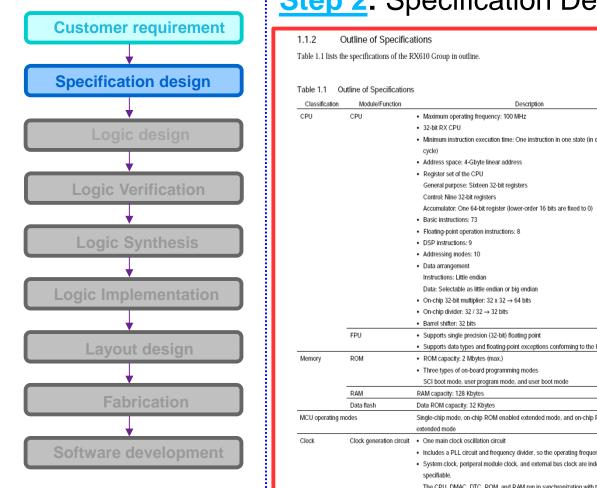


Step 2: Specification Design [Processor, IP, SoC, FE]

The demands of customers will be transferred into technique documents (specifications).

- ◆ Speed of the chip: 1 Ghz, 200 Mhz, 100 Khz ...
- How much power consumption of the chip
- How many implemented peripherals
- How many CPU cores
- How to design and verify this chip ...





Step 2: Specification Design Outline of Specifications Table 1.1 lists the specifications of the RX610 Group in outline.

General purpose: Sixteen 32-bit registers

Data: Selectable as little endian or big endian

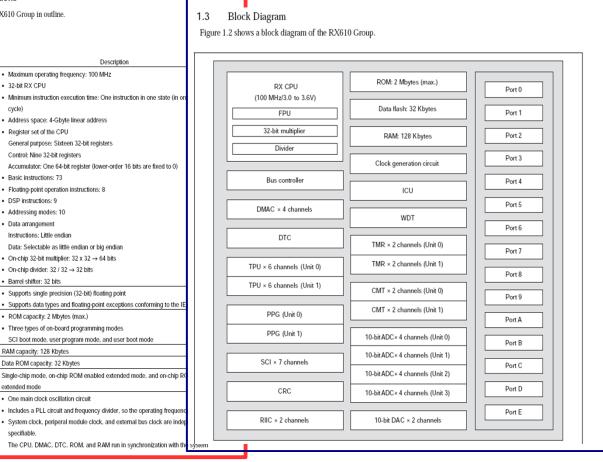
SCI boot mode, user program mode, and user boot mode

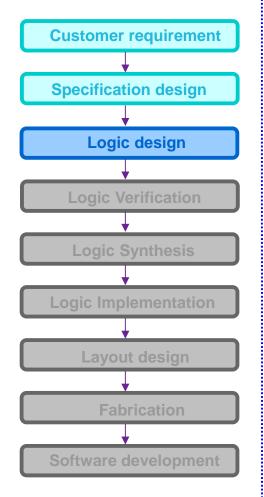
Accumulator: One 64-bit register (lower-order 16 bits are fixed to 0)

Control: Nine 32-bit registers

Instructions: Little endian

Description





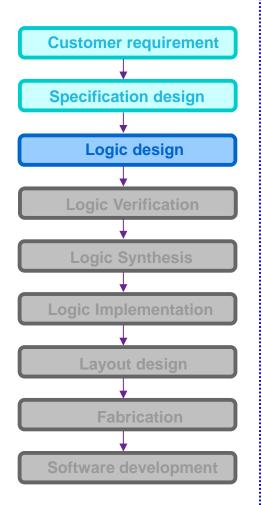
Step 3: Logic Design [Processor, IP, SoC, FE]

Logic Design or RTL (Register Transfer Level) Design is a step in which chip's specifications is designed by using HDL

(Hardware Design Language)

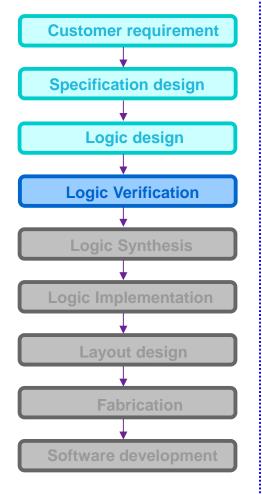
- Two commons HDL languages are Verilog and VHDL
 - → Verilog: Verification Logic [Verilog 1995, 2001, System *Veriloal*
 - → VHDL: VHSIC (Very High Speed Integrated Circuit) Hardware Design Language
- ◆ Today, Verilog is the most use in Hardware Design





Step 3: Logic Design [Processor, IP, SoC, FE]

```
// A flip-flop
module ff (clk,rst n,in,out);
                // clock signal
  input clk;
  input rst n; // reset signal
                // data input signal (1 bit)
   input in;
   output out; // data output signal (1 bit)
                // register contains output data
   reg out;
   // Reset data when rst n is 0
   // Update data for each rising clock when
  // rst n is 1
   always @(posedge clk) begin
     if (rst n == 1'b0) begin
        out <= 1'b0:
     end
     else begin
        out <= in:
     end
   end
endmodule
```

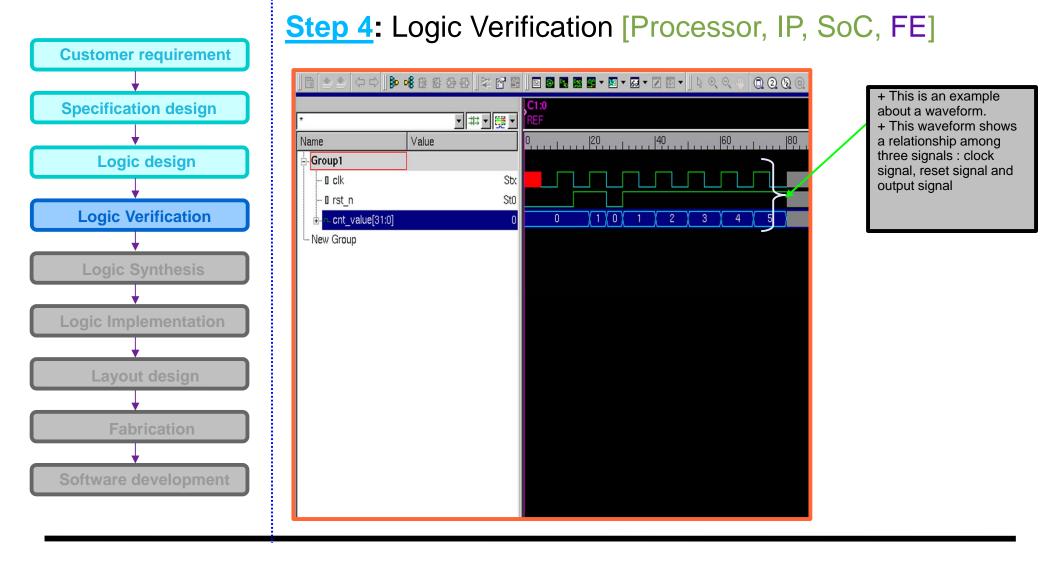


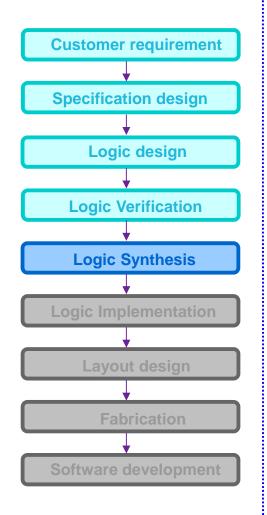
Step 4: Logic Verification [Processor, IP, SoC, FE]

This step is used to execute (simulate) RTL code on a simulator.

- To check whether functions of the RTL run correct or not.
- To check whether the timing (relationships among signals) of the chip run correct or not.





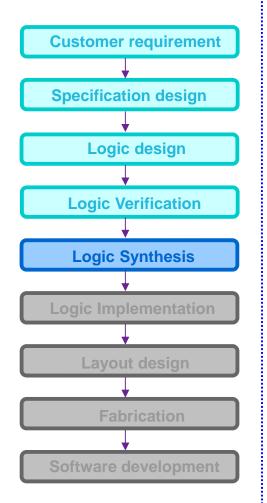


Step 5: Logic Synthesis [Processor, IP, SoC]

This step will transfer a RTL code into a gate net list

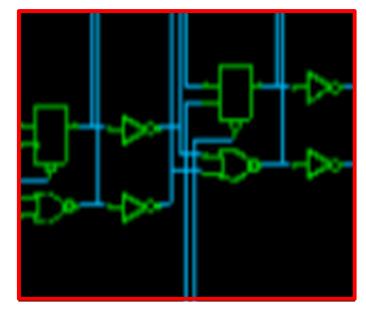
- ◆ The advantage of each production process will be displayed here. Each cell will have different characteristics such as area, power consumption ... according to a corresponding process such as 60 nm, 45 nm, 28 nm and etc.
- The smaller synthesized area, the more advantages a chip gains.



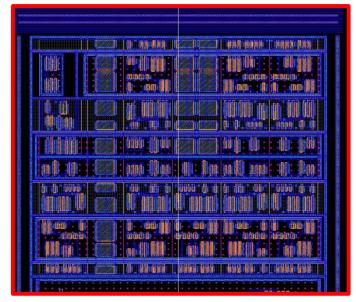


Step 5: Logic Synthesis

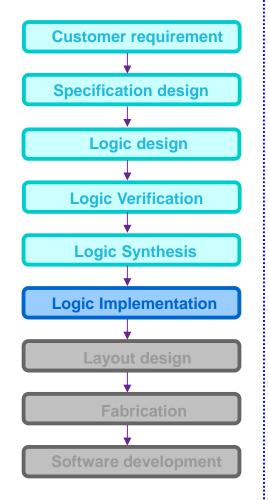
[Processor, IP, SoC, Circuit Design]



A gate net list



A part of the standard cell



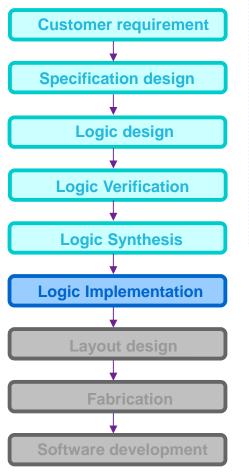
Step 6: Logic Implementation

[Logic Implementation, Processor, FE]

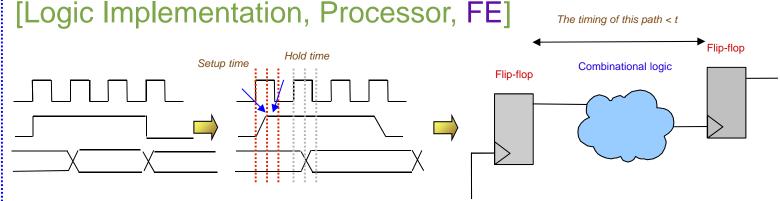
This step will work mainly on a gate net list for:

- Check timing of a chip in such field: hold/setup time, critical paths ...
- Add an extra gate net list for the DFT (Design For Test) function to enhance the later productivity





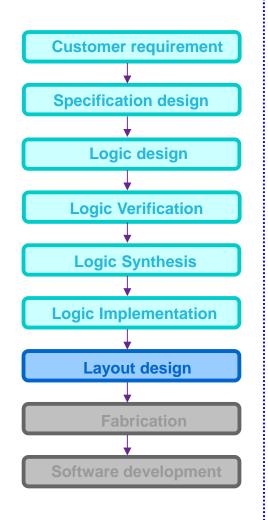
Step 6: Logic Implementation



DFT: During manufacturing, if a chip is defected, how do we diagnose the position of the error?



Add some circuits will help designers to find the correct position and fix the errors in some cases

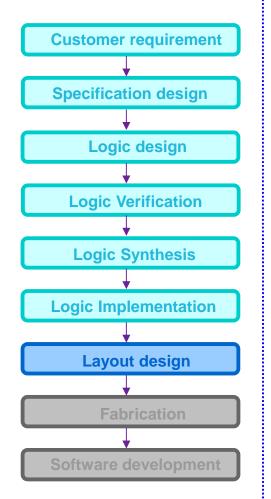


Step 7: Layout Design [Backend]

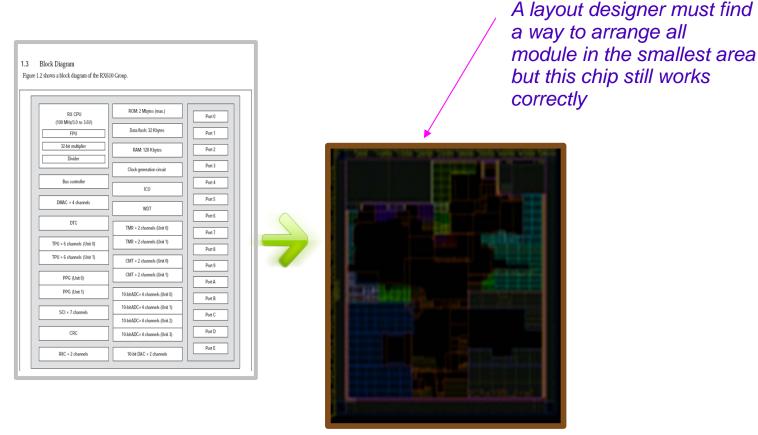
This step will work arrange the chip's gate net list into a specified area (wafer).

- Minimize the chip's area.
- Check physical conditions can affect to the chip during the arrangement process.
- Arrange power supply for a chip.
- Wiring signals, etc.

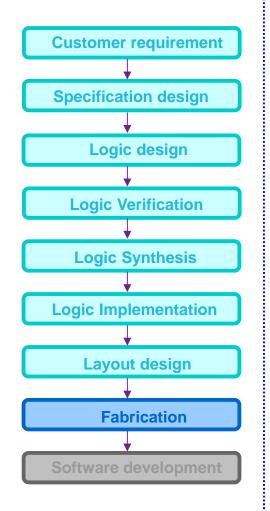








Each color is a module

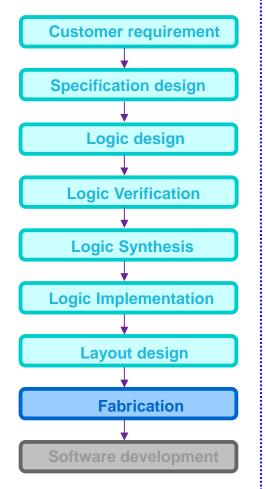


Step 8: Fabrication

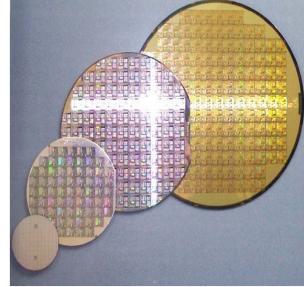
The chip will be produced and packaged in a manufacture

- This step will be done by Japanese factories
- Silicon (wafer) is a main material to product a chip
- A factory will cost from 3 ~ 4 billion to build.
- To product each manufacture process, a factory must be equipped with corresponding machines

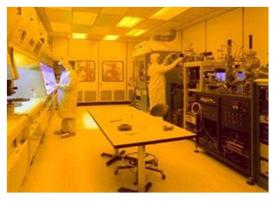




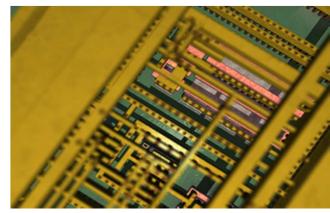
Step 8: Fabrication



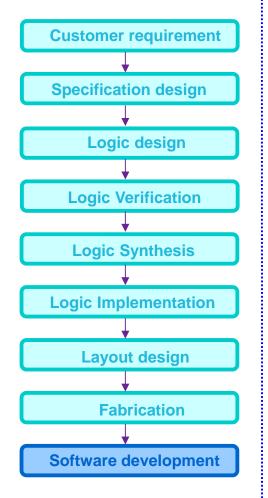
Wafer's sizes



Clean room to product chip



A chip on a wafer



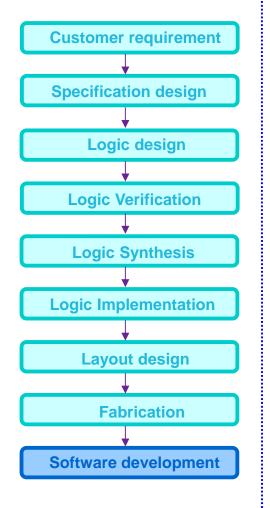
Step 9: Software development

[Software solution, Mobile platform, Software IP

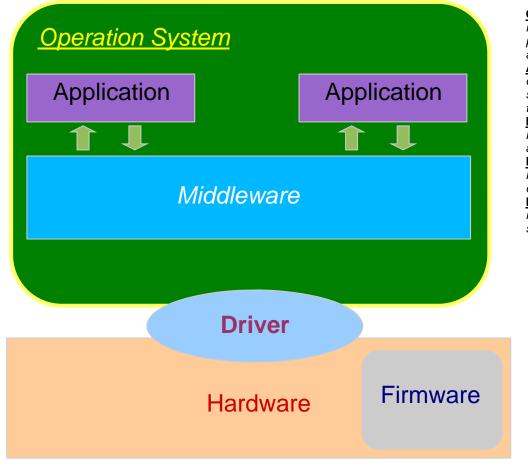
Processor, IP, and SoC]

This is the final step in developing a chip. Renesas will also provide a complete or, part of, software solution for customers through:

- Port a operation system on chip.
- Develop demonstration, application, firmwares, middle wares and drivers.
- Develop tool kits for third parties.



Step 9: Software development



Operation System:

manage hardware resources and provide efficient executions for applications

Application:

designed to help the user to perform singular or multiple related specific tasks

Middleware:

help to provide the communication among applications

Driver:

help operation system to manage operate hardware resources

Firmware:

integrated in a hardware to perform some particular functions.